





SURFACE MOUNT PRECISION ZENER DIODE

Features

- ±2.0% Tolerance on Breakdown Voltage
- Small, Low Profile Surface Mount Package
- Flat Lead Package Design for Low Profile and High Power Dissipation
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

- Case: SOD523
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin Annealed over Alloy 42 Leadframe.
 Solderable per MIL-STD-202, Method 208 <a>®3
- Weight: 0.001 grams (Approximate)



Top View

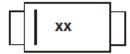
Ordering Information (Note 5)

Part Number	Qualification	Case	Packaging	
BZT585B5V1TQ-7	Automotive	SOD523	3,000/Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/quality/product_compliance_definitions/.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



xx = Product Type Marking Code (See Electrical Characteristics Table)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characte	ristic	Symbol	Value	Unit
Forward Voltage	@ I _F = 10mA @ I _F = 100mA	VF	0.9 1.1	V
Continuous Forward Current		I _F	200	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	350	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	$R_{\theta JA}$	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Note:

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Type	Marking	Zener Voltage Range (Note 7)		Maximum Zener Impedance (Note 8)		Temperature Coefficient	Total Capacitance	Maximum Reverse Current (Note 7)				
Number	Codes	V _Z @ I _{ZT}		I _{ZT}	Z _{ZT} @	Z _{ZK} @	I _{ZK}	TC @ I _{ZT}	$C_T @ f = 1MHz,$ $V_R = 0V$	I _R	@ V _R	
		Nom (V)	Min (V)	Max (V)	mA	2	Ω	mA	Typical (mV/°C)	Max (pF)	μΑ	V
BZT585B5V1TQ	3N	5.1	5.00	5.20	5	60	480	1	-0.5	300	2	2

Notes:

^{6.} Device mounted on FR-4 PCB with minimum recommended pad layout, as shown in Diodes Incorporated's Suggested Pad Layout document, which can be found on our website at http://www.diodes.com.

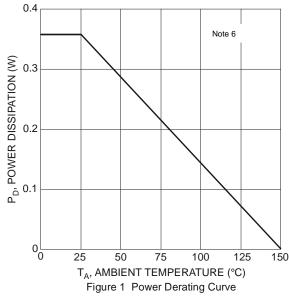
^{7.} Short duration pulse test used to minimize self-heating effect.

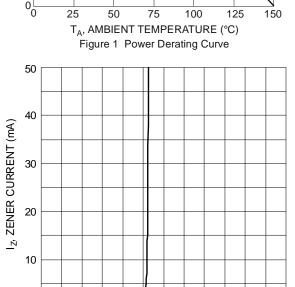
^{8.} f = 1kHz.

 $T_A = 25^{\circ}C$

1000 1200 1400 1600







1000

100

10

0.1 <u>200</u>

 $T_A = 85$ °C

T_A = 150°C

600

800

 V_F , INSTANTANEOUS FORWARD VOLTAGE(mV)

Figure 2 Typical Forward Characteristics

I_F, INSTANTANEOUS FORWARD CURRENT(mA)

 $\rm V_{\rm Z}$, ZENER VOLTAGE (V) Figure 3 Typical Zener Breakdown Characteristics

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Package Outline Dimensions

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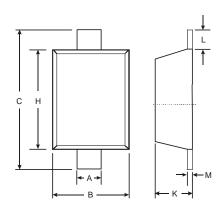
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Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

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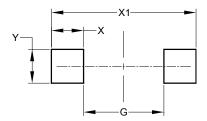


SOD523					
Dim	im Min Max				
Α	0.25	0.35			
В	0.70	0.90			
С	1.50	1.70			
Н	1.10	1.30			
K	0.55	0.65			
L	L 0.10 0.30				
M 0.10 0.12					
All Dimensions in mm					



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
G	0.80
Х	0.60
X1	2.00
Υ	0.70

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